positive electrode and negative electrode were thermally treated at a temperature of 150 °C under a vacuum of 10^{-2} Torr or lower, respectively.--

IN THE CLAIMS:

Cancel non-elected claims 12-20, 31 and 32 without prejudice or admission and subject to applicants' right to file a continuing application to pursue the subject matter of the non-elected claims.

Cancel claims 21-30 without prejudice or admission.

Kindly amend claims 1-11 as follows:

1. (Amended) A method for producing an electrical double layer capacitor, comprising the steps of:

assembling together components comprised of a positive electrode, a negative electrode, a non-aqueous solvent, an electrolyte containing a supporting salt, a separator, and a gasket to form a coin- or button-type electrical double layer capacitor; and

heating the assembled coin- or button-type electrical double layer capacitor.

2. (Amended) A method for producing an electrical double layer capacitor as claimed in claim 1; further

comprising the step of welding an outer connection terminal to the assembled coin- or button-type electrical double layer capacitor after the heating step.

3. (Amended) A method for producing an electrical double layer capacitor as claimed in claim 1; wherein the heating step comprises heating the assembled coin- or button-type electrical double layer capacitor at a temperature in a range of 180 to 300 °C.

4. (Amended) A method of mounting an electrical double layer capacitor on a circuit substrate, comprising the steps of:

providing a circuit substrate;

assembling together components comprised of a positive electrode, a negative electrode, a non-aqueous solvent, an electrolyte containing a supporting salt, a separator, and a gasket to form a coin- or button-type electrical double layer capacitor;

heating the assembled coin- or button-type electrical double layer capacitor;

arranging the heated assembled coin- or button-type electrical double layer capacitor on the circuit substrate; and

reflow soldering the heated assembled coin- or button-type electrical double layer capacitor on the circuit substrate.

5. (Amended) A method as claimed in claim 4; further comprising the step of welding an outer connection terminal to the assembled coin- or button-type electrical double layer capacitor.

6. (Amended) A method as claimed in claim 4; wherein a temperature profile of the heating step in a heating region under 150 °C is within a range of 50% to 150% of a temperature profile of the reflow soldering step in the heating region under 150 °C.

7. (Amended) A method as claimed in claim 4; wherein a duration of the heating step in a heating region under 150°C is within a range of 50% to 150% of a duration of the reflow soldering step in the heating region under 150°C.

8. (Amended) A method as claimed in claim 4; wherein a temperature profile of the heating step in a heating region of 150 to 180 °C is within a range of 80% to 120% of a temperature profile of the reflow soldering step in the heating region of 150 to 180 °C.

9. (Amended) A method as claimed in claim 5; wherein a duration of the heating step in a heating region of 150 to 180°C is within a range of 80% to 120% of a duration of the reflow soldering step in the heating region of 150 to 180 °C.

10. (Amended) A method as claimed in claim 4; wherein a temperature profile of the heating step in a heating region of 180 to 300 °C is within a range of 90% to 110% of a temperature profile of the reflow soldering step in the heating region of 180 to 300 °C.

11. (Amended) A method as claimed in claim 4; wherein a duration of the heating step in a heating region of 180 to 300 °C is within a range of 90% to 110% of a duration of the reflow soldering step in the heating region of 180 to 300 °C.

Kindly add the following new claims 33-55:

33. A method according to claim 1; wherein the assembling step comprises assembling together the components by caulk sealing the components.

34. A method according to claim 4; wherein the assembling step comprises assembling together the components by caulk sealing the components.

35. A method according to claim 4; wherein a temperature profile of the heating step is approximately the same as a temperature profile of the reflow soldering step.

36. A method for producing an electrical double layer capacitor, comprising the steps of: assembling together components comprised of a positive electrode, a negative electrode, a non-aqueous solvent, an electrolyte containing a supporting salt, a separator, and a gasket to form an electrical double layer capacitor containing a foreign substance; and heating the assembled electrical double layer capacitor to remove at least a substantial amount of the foreign substance contained in the assembled electrical double layer capacitor.

37. A method according to claim 36; wherein the assembled electrical double layer capacitor comprises a coin- or button-type electrical double layer capacitor.

38. A method according to claim 36; wherein the assembling step comprises assembling together the components by caulk sealing the components.

39. A method according to claim 36; further comprising the step of connecting a connection terminal to the assembled electrical double layer capacitor.

40. A method according to claim 39; wherein the connecting step comprises welding the connection terminal to the assembled electrical double layer capacitor.

41. A method according to claim 36; wherein the heating step comprises heating the assembled electrical double layer capacitor at a temperature in a range of 180 to 300 °C.

42. A method according to claim 36; further comprising the step of marking the heated assembled electrical double layer capacitor to distinguish the heated assembled electrical double layer capacitor from an assembled electrical double layer capacitor which has not been heated.

43. A method of mounting an electrical double layer capacitor on a circuit substrate, comprising the steps of: providing a circuit substrate; assembling together components comprised of a positive electrode, a negative electrode, a non-aqueous solvent, an electrolyte containing a supporting salt, a separator, and a gasket to form an electrical double layer capacitor containing a foreign substance; heating the assembled electrical double layer capacitor to remove at least a substantial amount of the foreign substance contained in the assembled electrical double layer capacitor; arranging the heated assembled electrical double layer capacitor on the

circuit substrate; and reflow soldering the heated assembled electrical double layer capacitor on the circuit substrate.

44. A method according to claim 43; wherein the assembled electrical double layer capacitor comprises a coin- or button-type electrical double layer capacitor.

45. A method according to claim 43; wherein the assembling step comprises assembling together the components by caulk sealing the components.

46. A method according to claim 43; further comprising the step of connecting a connection terminal to the assembled electrical double layer capacitor.

47. A method according to claim 46; wherein the connecting step comprises welding the connection terminal to the assembled electrical double layer capacitor.

48. A method according to claim 43; wherein the heating step comprises heating the assembled electrical double layer capacitor at a temperature in a range of 180 to 300 °C.

49. A method according to claim 43; wherein a temperature profile of the heating step in a heating region under 150 °C is within a range of 50% to 150% of a temperature profile of the reflow soldering step in the heating region under 150 °C.

50. A method according to claim 43; wherein a duration of the heating step in a heating region under 150°C is within a range of 50% to 150% of a duration of the reflow soldering step in the heating region under 150°C.

51. A method according to claim 43; wherein a temperature profile of the heating step in a heating region of 150 to 180 °C is within a range of 80% to 120% of a temperature profile of the reflow soldering step in the heating region of 150 to 180 °C.

52. A method according to claim 43; wherein a duration of the heating step in a heating region of 150 to 180°C is within a range of 80% to 120% of a duration of the reflow soldering step in the heating region of 150 to 180 °C.

53. A method according to claim 43; wherein a temperature profile of the heating step in a heating region of 180 to 300 °C is within a range of 90% to 110% of a temperature profile of the reflow soldering step in the heating region of 180 to 300 °C.

54. A method according to claim 42; wherein a duration of the heating step in a heating region of 180 to 300 °C is within a range of 90% to 110% of a duration of the reflow soldering step in the heating region of 180 to 300 °C.

55. A method according to claim 42; further comprising the step of marking the heated assembled electrical double layer capacitor to distinguish the heated assembled electrical double layer capacitor from an assembled electrical double layer capacitor which has not been heated.

IN THE ABSTRACT:

Delete the abstract now of record and insert therefor the new abstract submitted herewith on a separate sheet.

ADDITIONAL FEES:

Submitted herewith is a check in the amount of $36.00 to cover the additional fee for two (2) extra claims in excess of those already paid for. Should it be determined that a further fee is due, authorization is hereby given to charge any such fee to our Deposit Account No. 01-0268.

REMARKS

In the last Office Action, the Examiner withdrew claims 12-20, 31 and 32 from further consideration as being directed to a non-elected invention. Claims 4-11 and 25-30 were rejected under 35 U.S.C. §112, second paragraph, for indefiniteness. Claims 1-3 were rejected under 35 U.S.C.